Soldering Reflow:

Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

Max temperature: 260℃.

Max time at max temperature: 10 sec.

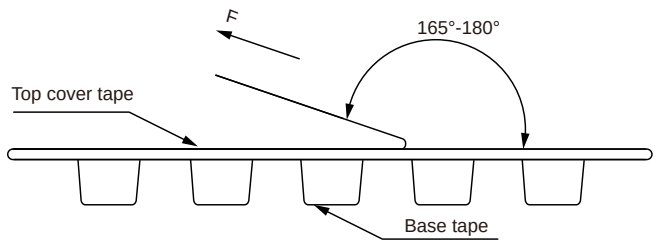
Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension:

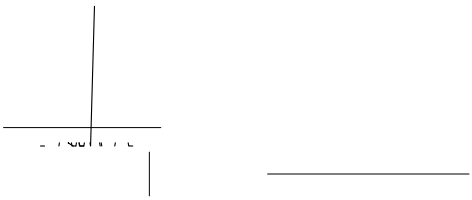
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTE6030	7.0 ± 0.1	6.8 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	12.0 ± 0.1	16.0 ± 0.3	3.3 ± 0.1	1.75 ± 0.1	0.35 ± 0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Reel Dimension：[mm]



Packaging Quantity: